



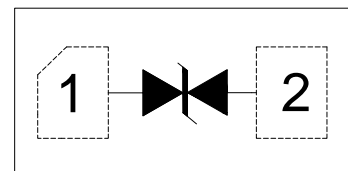
- ◇ Protects one bi-directional I/O line
- ◇ Low clamping voltage
- ◇ Low operating voltage:5.0V
- ◇ RoHS compliant
- ◇ AEC-Q101 qualified

- ◇ Cell phone handsets and accessories
- ◇ Personal digital assistants (PDA's)
- ◇ Notebooks, desktops, and servers
- ◇ Portable instrumentation
- ◇ Pagers
- ◇ Microprocessor based equipment

- ◇ DFN1006-2L package
- ◇ Molding compound flammability rating: UL 94V-0
- ◇ Quantity per reel: 10,000pcs
- ◇ Lead finish: lead free
- ◇ Marking code: PB



DFN1006-2L(Bottom view)



Pin Configuration(Top view)

FIG.3: Pulse derating curve

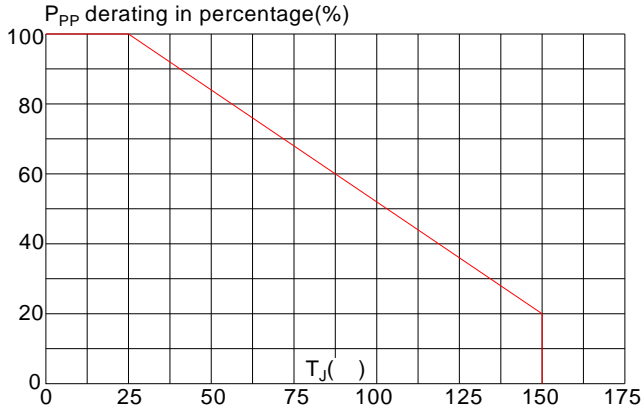
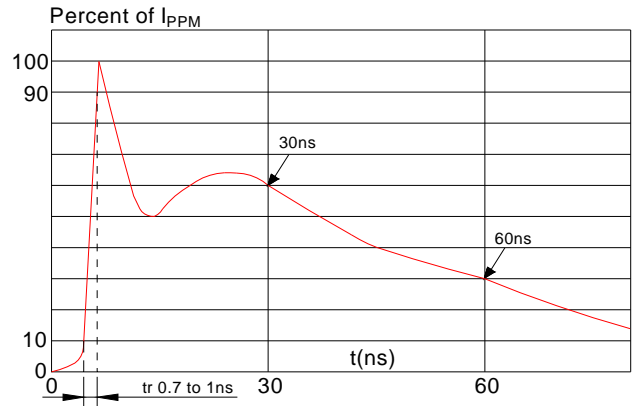
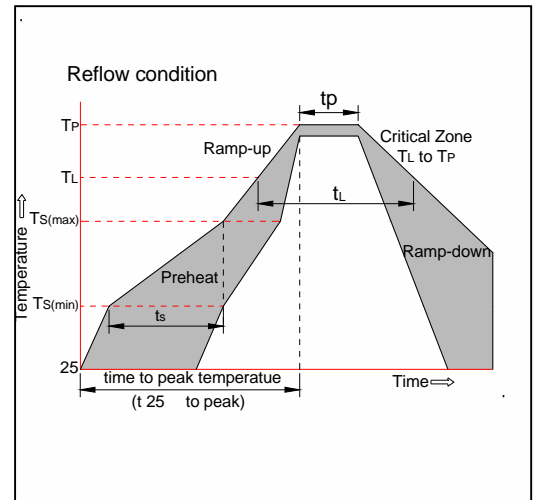
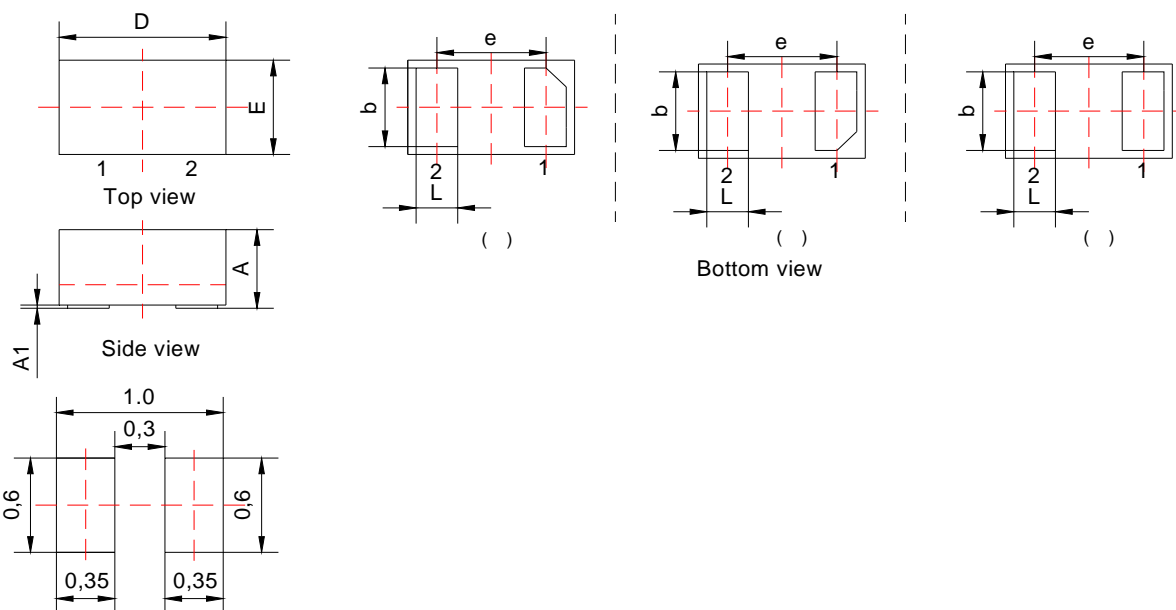


FIG.4: ESD clamping (30kV contact)



Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150
	-Temperature Max($T_{s(max)}$)	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3 /sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)
Time within 5 of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T_P)		8 min. Max
Do not exceed		+260





Recommended soldering footprint(mm)

Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.50	0.55	0.016	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65BSC			0.026BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012

Part Number

Marking Code